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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/019,201	12/20/2001	Kazuhiro Maeno	TIC-0010	9902	
7590 05/06/2004			EXAM	EXAMINER	
Michael P Dunnam			CHU, CHRIS C		
Woodcock Was 46th Floor	shburn		ART UNIT	PAPER NUMBER	
One Liberty Place			2815		
Philadelphia, PA 19103			DATE MAILED: 05/06/2004	4 ~	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicati p No	Anniinani/a)			
		Applicati n No.	Applicant(s)			
055		10/019,201	MAENO ET AL.			
	Offic Action Summary	Examiner	Art Unit			
		Chris C. Chu	2815			
Period fo	The MAILING DATE f this communication or Reply	appears n th c ver sheet with the c	orrespondence address			
THE I - Externanter - If the - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR RE MAILING DATE OF THIS COMMUNICATIOnsions of time may be available under the provisions of 37 CFI SIX (6) MONTHS from the mailing date of this communication experiod for reply specified above is less than thirty (30) days, a period for reply is specified above, the maximum statutory per to reply within the set or extended period for reply will, by streply received by the Office later than three months after the med patent term adjustment. See 37 CFR 1.704(b).	NN. R 1.136(a). In no event, however, may a reply be tin. I reply within the statutory minimum of thirty (30) day rivod will apply and will expire SIX (6) MONTHS from atute, cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).			
Status						
1) 又	Responsive to communication(s) filed on 1	7 February 2004.				
, —	·	This action is non-final.				
,						
Dispositi	ion of Claims					
5)□ 6)⊠ 7)□	Claim(s) 1 - 10 is/are pending in the application of the above claim(s) is/are with Claim(s) is/are allowed. Claim(s) 1 - 10 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction are	drawn from consideration.				
Applicati	ion Papers					
10)	The specification is objected to by the Example The drawing(s) filed on is/are: a) Applicant may not request that any objection to Replacement drawing sheet(s) including the control of the oath or declaration is objected to by the	accepted or b) objected to by the the drawing(s) be held in abeyance. Serrection is required if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CFR 1.121(d).			
,		e Examiner. Note the attached Office	Addon of format 10-102.			
12)⊠ a)l	Acknowledgment is made of a claim for fore All b) Some * c) None of: 1. Certified copies of the priority docum 2. Certified copies of the priority docum 3. Copies of the certified copies of the papplication from the International Bu See the attached detailed Office action for a	nents have been received. nents have been received in Applicati priority documents have been receive reau (PCT Rule 17.2(a)).	on No ed in this National Stage			
2) Notice 3) Information	ot(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SE er No(s)/Mail Date					

Application/Control Number: 10/019,201

Art Unit: 2815

DETAILED ACTION

Response to Amendment

1. Applicant's amendment filed on September 11, 2003 has been received and entered in the case.

Claim Objections

2. Claim 1 is objected to because of the following informalities: In claim 1, line 9, "or wiring pattern" [sic: or a wiring pattern]. Appropriate correction is required.

Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 4. Claims 1-4 and 6-10 are rejected under 35 U.S.C. 102(b) as being anticipated by Iwasa et al. '040.

Regarding claim 1, Iwasa et al. discloses in e.g., Fig. 15, Fig. 16 and column 1, line 61 - column 2, line 47 a semiconductor device (100), comprising:

- a plurality of semiconductor elements (switching elements; column 2, lines 32
 33) arranged on a substrate (HS); and
- a main current electrode (M1 or M2), which is formed by a piece of metal (indicates by the designation M1 or M2), which is arranged near said plurality

Page 3

Art Unit: 2815

of semiconductor elements and vertically apart from the surface of the substrate, wherein;

- each of said plurality of semiconductor elements (switching elements) and said main current electrode are electrically connected, and
- wherein said main current electrode bridges from one end of the substrate to an opposite end of the substrate (because the length M1 or M2 from one endcurved portion to the other end-curved portion is bigger than one end of the element HS to an opposite end of the element HS) and is arranged immediately above one of said plurality of semiconductor elements (switching elements) or a wiring pattern (wiring patterns on BS) connected to the one of said plurality of semiconductor elements.

Regarding claim 2, Iwasa et al. discloses in e.g., Fig. 15 and column 1, line 61 column 2, line 47 each of said plurality of semiconductor elements and said main current electrode being connected by wire bonding (wires; see e.g., Fig. 15).

Regarding claim 3, Iwasa et al. discloses in e.g., Fig. 16 and column 1, line 61 column 2, line 47 the plurality of semiconductor elements being switching elements (column 2, lines 32 - 33).

Regarding claim 4, Iwasa et al. discloses in e.g., Fig. 16 and column 1, line 61 column 2, line 47 a thermal conductor member (BS) at a bottom of the semiconductor device, wherein said plurality of semiconductor elements are directly or indirectly connected to said thermal conductor member so that they are thermally coupled.

Application/Control Number: 10/019,201

Art Unit: 2815

Regarding claim 6, Iwasa et al. discloses in e.g., Fig. 16 and column 1, line 61 - column 2, line 47 said plurality of semiconductor elements being arranged in one row or a plurality of rows.

Regarding claim 7, Iwasa et al. discloses in e.g., Fig. 15, Fig. 16 and column 1, line 61 - column 2, line 47 a semiconductor device (100) including one or a plurality of semiconductor elements (switching elements; column 2, lines 32 – 33), comprising:

- a substrate (HS) on which the one or the plurality of semiconductor elements are arranged;
- a case (CS) that is arranged in a predetermined position relative to said substrate so that one of the plurality of semiconductor elements are surrounded; and
- a metal member (the curved portion or mid-portion of the M1 or M2) on which a main current electrode (M1 or M2) of the one of the plurality of semiconductor elements and a terminal (the foot portions that is part of the elements M1 and M2 and connected to the wiring patterns on the BS) for electrically connecting said semiconductor device and a circuit external to said semiconductor device are formed integrally,
- wherein said metal member (indicates by the designation M1 or M2) is arranged in a position apart from said substrate by using said case without directly contacting said substrate, and wherein said metal member bridges from one end of the substrate to an opposite end of the substrate (because the length M1 or M2 from one end-curved portion to the other end-curved portion

is bigger than one end of the element HS to an opposite end of the element HS).

Regarding claim 8, Iwasa et al. discloses in e.g., Fig. 16 and column 1, line 61 - column 2, line 47 said metal member being arranged above the one or the plurality of semiconductor elements or a wiring pattern connected to the one or the plurality of semiconductor elements.

Regarding claim 9, Iwasa et al. discloses in e.g., Fig. 15, Fig. 16 and column 1, line 61 - column 2, line 47 said metal member and the semiconductor device being electrically connected by wire bonding (wires).

Regarding claim 10, Iwasa et al. discloses in e.g., Fig. 15, Fig. 16 and column 1, line 61 - column 2, line 47 said case (CS) including a frame portion surrounding the one or the plurality of semiconductor elements; and said metal member is fixed to the frame portion of said case.

Claim Rejections - 35 USC § 103

- 5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 6. Claim 5 is rejected under 35 U.S.C. 103(a) as being unpatentable over Iwasa et al. and Masumoto et al. as applied to claim 4 above, and further in view of Noro et al. '337.

Application/Control Number: 10/019,201

Art Unit: 2815

Sugawara et al. discloses the claimed invention except for the material of the thermal conductor member being formed with a ceramic material. However, Noro et al. teaches in column 3, lines 23 - 25 the material of a thermal conductor member being formed with a ceramic material. Thus, it would have been obvious to one of ordinary skill in the art at the time when the invention was made to further modify Iwasa et al. by using the ceramic material for the thermal conductor member as taught by Noro et al. The ordinary artisan would have been motivated to further modify Iwasa et al. in the manner described above for at least the purpose of providing good connections and packages for the LSI chips in a high density and shortening the total wiring length of wirings (column 3, lines 28 - 32).

Response to Arguments

7. Applicant's arguments with respect to claims 1 and 7 have been considered but are most in view of the new ground(s) of rejection.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not

mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Chris C. Chu whose telephone number is 571-272-1724. The examiner can normally be reached on 11:30 - 8:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on 517-272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you

have questions on access to the Private PAIR system, contact the Electronic Business

Center (EBC) at 866-217-9197 (toll-free).

BRADLEY BAUMEISTER PRIMARY EXAMINER

Chris C. Chu Examiner Art Unit 2815